

Electronic Patent Application Fee Transmittal

Application Number:	10552540			
Filing Date:	11-Oct-2005			
Title of Invention:	Thermosetting resin composition, multilayer body using same, and circuit board			
First Named Inventor/Applicant Name:	Shigeru Tanaka			
Filer:	Dariush G. Adli/Firoozeh Vakilzadeh			
Attorney Docket Number:	81844.0044			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Independent claims in excess of 3	1614	1	210	210
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				210